



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

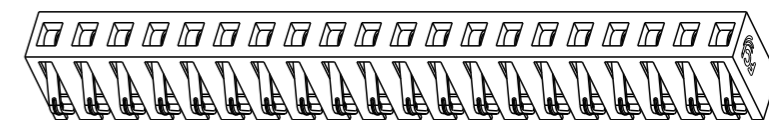
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT NO.	PACKAGING
10100774-001LF	TUBE

50.800±0.127
(20 POSITIONS X 2.540)
48.260±0.127



SCALE 2.000

1.270 REF.

8.480 REF.

0.380 REF.

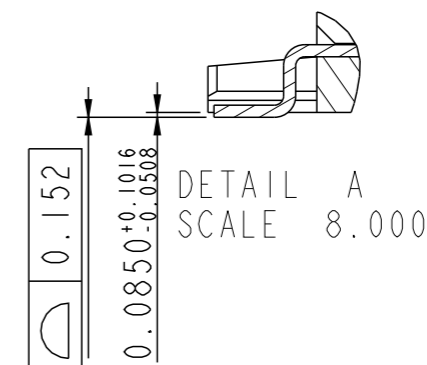
3.810 REF.

1.140

45.720 REF.

48.260 REF.

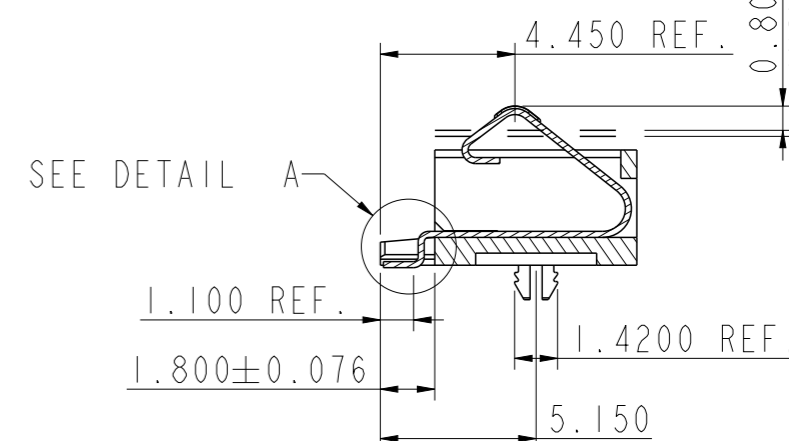
SEE NOTE 4



DETAIL A
SCALE 8.000

0.80 (NOMINAL COMPRESSION)

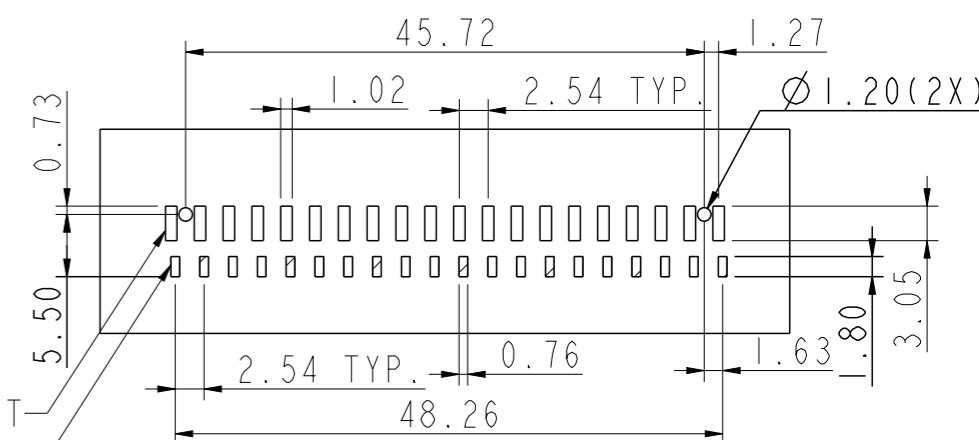
1.00 (FULLY COMPRESSION)



SECTION A-A

NOTES:

- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0, BLACK
TERMINAL & CLIP: COPPER ALLOY
- PLATING:
TERMINAL: 0.76um MIN. Au ON CONTACT AREA, 2.54um MIN. Sn(100% MATTE TIN) ON SOLDER TAILS, 1.27um MIN. Ni UNDERPLATE OVERALL
CLIP: 2.54um MIN. Sn(100% MATTE TIN) OVER 1.27um MIN. Ni UNDERPLATE OVERALL
- NORMAL FORCE PER EACH TERMINAL SHOULD BE 50gf MIN. ~ 200gf MAX. AT NOMINAL COMPRESSION HEIGHT AT 25±6mm/min COMPRESSION SPEED
- VENDOR ID TO BE ON AREA INDICATED
- PRODUCT SPECIFICATION: GS-12-626
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN



CONTACT PAD LAYOUT
SOLDER PAD LAYOUT

SCALE 1.500
RECOMMENDED SOLDER AND CONTACT PAD LAYOUT

spec ref	-	dr	Jeffrey Lim	2011/09/16	projection	mm	size	A3	scale	4.000
tolerance std	ISO 406 ISO 1101	eng	Jeffrey Lim	2011/10/11		mm	A3	-	-	-
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-						
surface	ISO 1302	appr	Joey Ng	2011/10/12	product family		rel level	Released		
	linear	0.X	±0.35		title 20P COMPRESSION CONNECTOR	dwg no 10100774	rev A			
		0.XX	±0.30							
		0.XXX	±0.130							
	angular	0°	±2°	www.fci.com	cat. no.	Product - Customer Drw	sheet 1 of 1			